

C0603C471J2TACTU

Aliases (C0603C471J2TAC7867)

SMD Comm X8G HT150C, Ceramic, 470 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	3.7 mg	
Shelf Life	78 Weeks	
MSL	1	

470 pF

1 MHz 1.0Vrms

100 GOhms

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

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Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm
Packaging Specifications	

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Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Reference to +25°C and 0 VDC Applied (TCC)	
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
	Dielectric Withstanding Voltage Temperature Range Temp. Coefficient Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) Dissipation Factor

Specifications

Measurement Condition

Insulation Resistance

Capacitance

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